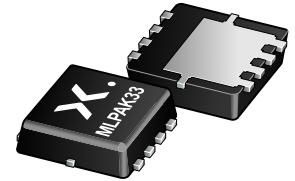


# Full Material Declaration for PXN011-100QS

Date	2025-11-25 14:24:13 CET+0100
Package	<u>SOT8002-1</u> (MLPAK33): 0.8 mm × 3.3 mm × 3.3 mm
Description	N-ch 11mohm, Standard level in MLPAK33
Datasheet	<a href="https://assets.nexperia.com/documents/data-sheet/PXN011-100QS.pdf">https://assets.nexperia.com/documents/data-sheet/PXN011-100QS.pdf</a>
OPNs	934665768118: PXN011-100QSJ (RFS), MSL 1
Automotive-qualified	No
UL-94	<a href="https://iq.ulprospector.com/en/profile?e=575924">https://iq.ulprospector.com/en/profile?e=575924</a>



REACH	Compliant with Regulation 1907/2006/EC (REACH). Does not contain REACH SVHC substances exceeding 1000 ppm of the article.
EU RoHS	Compliant with Directive 2011/65/EU, amended by Directive 2015/863/EU, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ('RoHS 2 amended') without exemptions.
CN RoHS	Compliant with Chinese ACEP (Administration on the Control of Pollution Caused by Electronic Information Products) (CN RoHS) without exemptions.
ELV	Compliant with Directive 2000/53/EC, amended by Directive 2023/533, on end of life vehicles (ELV) without exemptions.
PFAS	Does not contain any intentionally added per- and polyfluoroalkyl substances (PFAS).
CA Proposition 65	Contains California Proposition 65 substance(s) [at the article level]: substance 7439-92-1: 43 ppm; substance 1333-86-4: 844 ppm;
IEC 62474	Contains IEC 62474 substance(s) [at the article level]: substance 7439-92-1: 43 ppm; substance 1333-86-4: 844 ppm;
Precious Metals	Contains precious metals [Ag, Au, Pd, Pt; at the article level]: substance 7440-22-4: 10170 ppm; substance 7440-05-3: 1 ppm;
GADSL	Contains 'Global Automotive Declarable Substances List' (GADSL) substances: substance 7440-22-4: 10170 ppm; substance 7440-05-3: 1 ppm; substance 7440-50-8: 422832 ppm; substance 7439-92-1: 43 ppm;
RHF Indicator	D: Lead-free and halogen-free according to Nexperia's halogen-free definition.

Material	Mat. Group	Substance	CAS No.	Mass / mg	Mass-% of Material	Mass-% of Part
Adhesive	Filler	Silver (Ag)	7440-22-4	0.184800	80.000000	0.805977
Adhesive	Polymer	Poly(isobornyl) methacrylate	64114-51-8	0.023100	10.000000	0.100747
Adhesive	Polymer	Bismaleimide resin		0.020213	8.750000	0.088156
Adhesive	Polymer	Polysiloxanes	63148-53-8	0.002310	1.000000	0.010075
Adhesive	Polymer	Acrylic resin		0.000554	0.240000	0.002416
Adhesive	Curing accelerators/Catalyst	Palladium (Pd)	7440-05-3	0.000023	0.010000	0.000100
<b>Adhesive Total</b>				<b>0.231000</b>	<b>100.000000</b>	<b>1.007471</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	2.131950	100.000000	9.298172
<b>Die Total</b>				<b>2.131950</b>	<b>100.000000</b>	<b>9.298172</b>
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	9.399277	97.110000	40.993502
Lead Frame	Copper alloy	Iron (Fe)	7439-89-6	0.222617	2.300000	0.970910
Lead Frame	Copper alloy	Phosphorus (P)	7723-14-0	0.006775	0.070000	0.029548
Lead Frame	Copper alloy	Lead (Pb)	7439-92-1	0.000968	0.010000	0.004222
Lead Frame	Copper alloy	Zinc (Zn)	7440-66-6	0.000968	0.010000	0.004222
<i>Base Alloy C19400 Total</i>				<i>9.630605</i>	<i>99.500000</i>	<i>42.002404</i>
Lead Frame	Pure metal layer	Silver (Ag)	7440-22-4	0.048395	0.500000	0.211067
<i>Pre-Plating Total</i>				<i>0.048395</i>	<i>0.500000</i>	<i>0.211067</i>
<b>Lead Frame Total</b>				<b>9.679000</b>	<b>100.000000</b>	<b>42.213471</b>
Mould Compound	Filler	Silica fused	60676-86-0	8.780408	86.150000	38.294400
Mould Compound	Polymer	Epoxy resin system		0.883646	8.670000	3.853886

Material	Mat. Group	Substance	CAS No.	Mass / mg	Mass-% of Material	Mass-% of Part
Mould Compound	Hardener	Phenolic resin		0.437237	4.290000	1.906942
Mould Compound	Additive	Non-declarable		0.041787	0.410000	0.182248
Mould Compound	Filler	Silica	7631-86-9	0.029557	0.290000	0.128908
Mould Compound	Pigment	Carbon black	1333-86-4	0.019365	0.190000	0.084457
<b>Mould Compound Total</b>				<b>10.192000</b>	<b>100.000000</b>	<b>44.450841</b>
Post-Plating	Tin solder	Tin (Sn)	7440-31-5	0.398761	99.940000	1.739135
Post-Plating	Impurity	Non-declarable		0.000221	0.055500	0.000964
Post-Plating	Impurity	Lead (Pb)	7439-92-1	0.000018	0.004500	0.000078
<b>Post-Plating Total</b>				<b>0.399000</b>	<b>100.000000</b>	<b>1.740177</b>
Wire	Pure metal	Copper (Cu)	7440-50-8	0.295720	99.990000	1.289737
Wire	Impurity	Non-declarable		0.000030	0.010000	0.000131
<b>Wire Total</b>				<b>0.295750</b>	<b>100.000000</b>	<b>1.289868</b>
<b>PXN011-100QS Total</b>				<b>22.928700</b>	<b>100.000000</b>	<b>100.000000</b>

部件名称 Material	有毒或有害物质和元素 (Toxic or hazardous substances and elements)					
	铅 (Pb)	镉 (Cd)	汞 (Hg)	六价铬 (Cr <sup>6+</sup> )	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
胶黏剂 (Adhesive)	○	○	○	○	○	○
半导体芯片 (Die)	○	○	○	○	○	○
基底合金 (Base Alloy)	○	○	○	○	○	○
预镀层 (Pre-Plating)	○	○	○	○	○	○
模封料 (Mould Compound)	○	○	○	○	○	○
后镀层 (Post-Plating)	○	○	○	○	○	○
导线 (Wire)	○	○	○	○	○	○

○ 表示该有害物质在该部件所有均质材料中的含量均在 GB/T 26572 规定的限量要求以下  
Indicates that said hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement of GB/T 26572.

× 表示该有害物质至少在该部件的某一均质材料中的含量超出 GB/T 26572 规定的限量要求  
Indicates that said hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement of GB/T 26572.



该半导体产品具有无限期的环保使用期限 (EFUP)。  
This semiconductor product has an indefinite environmental friendly use period (EFUP).

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